





# IFN147 N-Channel JFET

#### Features

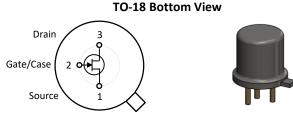
- InterFET N0450H Geometry
- Low Noise: 1.1 nV/vHz Typical
- High Gain: 30mS Typical
- RoHS Compliant
- SMT, TH, and Bare Die Package options.

#### **Applications**

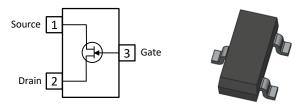
- Low-Noise Audio Amplifier
- Replacement for Japanese 2SK147

#### Description

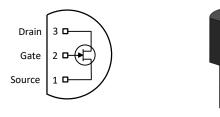
The -50V InterFET IFN147 is a low noise high gain replacement for the Japanese 25K147 JFET. Gate leakages are typically less than 50pA at room temperatures. The TO-18 package is hermetically sealed and suitable for military applications.







**TO-92 Bottom View** 



#### **Product Summary**

	Parameters	IFN147 Min	Unit
BV <sub>GSS</sub>	Gate to Source Breakdown Voltage	-40	V
I <sub>DSS</sub>	Drain to Source Saturation Current	5	mA
V <sub>GS(off)</sub>	Gate to Source Cutoff Voltage	-0.3	V
GFS	Forward Transconductance	20	mS

#### Ordering Information Custom Part and Binning Options Available

Part Number	Description	Case	Packaging
IFN147	Through-Hole	TO-18	Bulk
PN147	Through-Hole	TO-92	Bulk
SMP147	Surface Mount	SOT23	Bulk
	7" Tape and Reel: Max 3,000 Pieces		Minimum 1,000 Pieces
SMP147TR	13" Tape and Reel: Max 9,000 Pieces	SOT23	Tape and Reel
IFN147COT	Chip Orientated Tray (COT Waffle Pack)	СОТ	400/Waffle Pack
IFN147CFT	Chip Face-up Tray (CFT Waffle Pack)	CFT	400/Waffle Pack



**Disclaimer:** It is the Buyers responsibility for designing, validating and testing the end application under all field use cases and extreme use conditions. Guaranteeing the application meets required standards, regulatory compliance, and all safety and security requirements is the responsibility of the Buyer. These resources are subject to change without notice.







# **Electrical Characteristics**

# Maximum Ratings (@ T<sub>A</sub> = 25°C, Unless otherwise specified)

	Parameters	Value	Unit
VRGS	Reverse Gate Source and Gate Drain Voltage	-40	V
$I_{FG}$	Continuous Forward Gate Current	10	mA
PD	Continuous Device Power Dissipation	300	mW
Р	Power Derating	2.4	mW/°C
Τı	Operating Junction Temperature	-55 to 125	°C
T <sub>STG</sub>	Storage Temperature	-65 to 200	°C

### **Static Characteristics** (@ TA = 25°C, Unless otherwise specified)

			IFN113		
	Parameters	Conditions	Min	Max	Unit
V(BR)GSS	Gate to Source Breakdown Voltage	V <sub>DS</sub> = 0V, I <sub>G</sub> = -1µA	-40		v
IGSS	Gate to Source Reverse Current	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V, T <sub>A</sub> = 25°C V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V, T <sub>A</sub> = 150°C		-1 -1	nA μA
V <sub>GS(OFF)</sub>	Gate to Source Cutoff Voltage	$V_{DS}$ = 10V, $I_{D}$ = 1 $\mu$ A	-0.3	-1.2	v
I <sub>DSS</sub>	Drain to Source Saturation Current	$V_{GS} = 0V, V_{DS} = 10V$ (Pulsed)	5	30	mA

### **Dynamic Characteristics** (@ TA = 25°C, Unless otherwise specified)

			IFN147			
	Parameters	Conditions	Min	Тур	Max	Unit
G <sub>FS</sub>	Forward Transconductance	$V_{DS} = 10V, V_{GS} = 0V, I_{DSS} = 5mA,$ f = 1kHz	20	30		mS
Ciss	Input Capacitance	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1kHz			75	pF
Crss	Reverse Transfer Capacitance	V <sub>DS</sub> = 10V, I <sub>D</sub> = 0A, f = 1kHz			15	pF
NF	Noise Figure	$V_{DS} = 10V, I_D = 5mA, f = 1kHz$ $R_G = 100\Omega$ f = 100Hz		1	10	dB



Technical

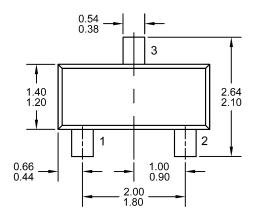
Support

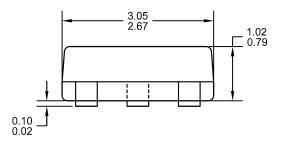
Order

Now

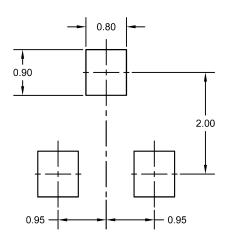
# SOT23 (TO-236AB) Mechanical and Layout Data

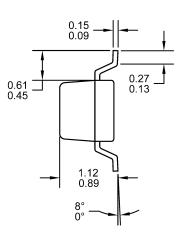
### **Package Outline Data**





### **Suggested Pad Layout**





- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.12 grams
- 3. Molded plastic case UL 94V-0 rated
- For Tape and Reel specifications refer to InterFET CTC-021 Tape and Reel Specification, Document number: IF39002
- 5. Bulk product is shipped in standard ESD shipping material
- 6. Refer to JEDEC standards for additional information.

- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided for reference only. A more robust pattern may be desired for wave soldering.



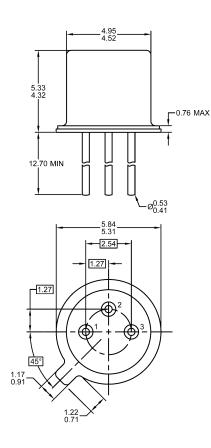


Order

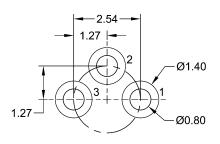
Now

# **TO-18 Mechanical and Layout Data**

### **Package Outline Data**



### Suggested Through-Hole Layout



- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.29 grams
- 3. Bulk product is shipped in standard ESD shipping material
- 4. Refer to JEDEC standards for additional information.

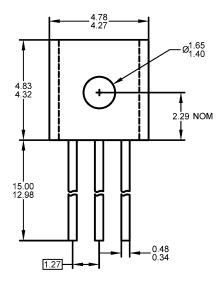
- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.

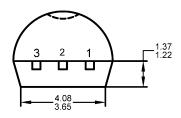




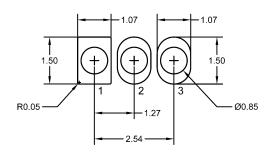
# **TO-92 Mechanical and Layout Data**

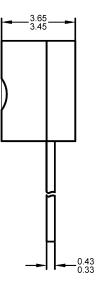
### **Package Outline Data**





### Suggested Through-Hole Layout





- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.19 grams
- 3. Molded plastic case UL 94V-0 rated
- 4. Bulk product is shipped in standard ESD shipping material
- 5. Refer to JEDEC standards for additional information.

- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.

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